Call For Papers - SLIP 2006

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8th International Workshop on
System Level Interconnect Prediction

March 4-5, 2006
Munich, Germany

The System Level Interconnect Prediction (SLIP) Workshop focuses on the modeling and prediction of usable properties of optimized interconnect systems and their impact on system performance. Both theory and applications of interconnect prediction techniques are highlighted, with emphasis on applications to architectural and micro-architectural exploration, physical design, interconnect technology planning and communication networks. In addition to the presentation of state-of-the-art papers in these fields, invited talks and tutorials by leading researchers aim to encourage discussions between the architecture, physical design, and interconnect technology communities.

Paper submission deadline: November 18, 2005

Scope

- Interconnect prediction methodology:
  - Statistical properties of complex interconnect systems
  - Techniques and calibrations for "Rentian" and "non-Rentian" interconnect estimation
  - A priori, on-line, or a posteriori estimation of interconnect design parameters (wire length, area, power, delay, ...)
- Applications in system design:
  - Interconnect parameter and yield estimation for use in architecture design and CAD
  - Interconnect planning flows for specific objectives (e.g., low power, high performance) or target technologies (e.g., ASIC/SoC, FPGA, System-in-package, 3-D integration, molecular/nanoelectronics)
- Applications in technology evaluation:
  - Interconnect technology prediction for long-term industry roadmap projections
  - Early (predictive) evaluation of novel interconnect technologies in a system's context
  - Architectural and micro-architectural effects of interconnect optimization approaches

Authors are invited to electronically submit papers of up to 8 pages in ACM proceedings format by following the instructions at http://www.softconf.com/start/SLIP2006. Proposals for sessions are also welcomed, and should be directed to the program committee. The proceedings of SLIP 2006 will be published by ACM Press. As in previous years, we anticipate a special issue of a major journal to be dedicated to SLIP 2006. The SLIP 2006 workshop will be co-located with and followed by DATE'06 (Design Automation and Test in Europe - www.date-conference.com).

www.SLIPonline.org